Intel® XMM™ 6255

Ultra Slim Modem for Internet of Things, 3G Smartphones, Machine-to-Machine (M2M) and Unconventional Client Devices

The Intel® XMM™ 6255 modem platform combines the Intel® X-GOLD™ 625 baseband and its integrated power management unit with the Intel SMARTi™ UE2p – the first transceiver with a fully integrated 3G power amplifier.

XMM™ 6255 is extraordinarily compact with an effective board area of ~300mm², making it ideal for unconventional form factors such as Internet of Things devices, wearables and M2M applications. Built-in controls protect the transceiver and integrated PA from dangers such as overheating, voltage peak and overcurrent that can occur under tough usage conditions.

2G >> **3G** >> 4G >> Connectivity

HSPA

(intel®)
Look Inside.™

Key Features

- Dual-band HSPA @ 7.2/5.76 Mbps DL/UL – single receiver
- Integrated 3G power amplifier
- Quad-band 2G optional with external, low-cost companion PA
- Co-designed isoplexer
- Direct to battery power
- Integrated DC/DC converters
- Digitally controlled crystal-oscillator (DCXO) support
- Intel X-GOLD™ 625 baseband
- Intel SMARTi™ UE2p transceiver with Intel® Power Transceiver technology
- Intel protocol stack
- Pre-certified
- A-GPS optional

HSPA	2G Optional	Isoplexer
Small PCB	Integrated Power Amplifier	1-chip BB & PMU

| | | A-GPS Optional |

Intel® Power Transceiver Technology Reduces BOM Costs

XMM™ 6255 features Intel® Power Transceiver technology, which combines 3G transmit & receive functionality, a fully integrated power amplifier, and power management on a single-chip SMARTi™ UE2p transceiver. This unique design helps minimize modem size and BOM costs.

RF Transceiver
+
Power Amplifier

Intel® XMM™ 6255

SMARTi™ UE2p
Transceiver Chip

X-GOLD™ 625
Baseband Processor Chip
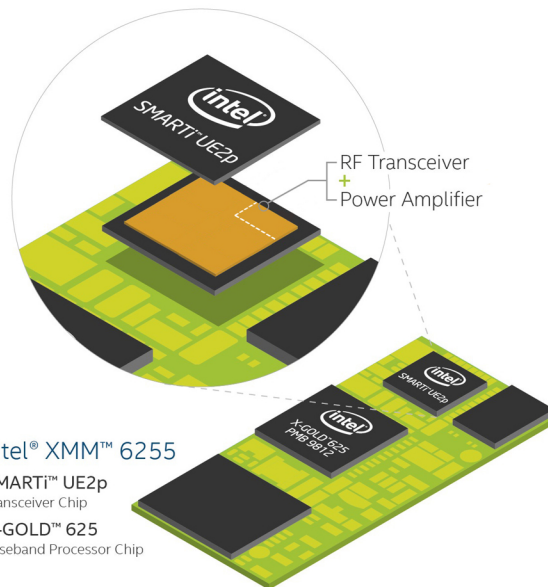
For more information on Intel® XMM™ 6255, visit www.intel.com/mobilecommunications